

Joe L Gonzalez

List of Publications by Year in descending order

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12
papers

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1684188
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12
docs citations

12
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40
citing authors

#	ARTICLE	IF	CITATIONS
1	A Substrate-Agnostic, Submicrometer PSAS-to-PSAS Self-Alignment Technology for Heterogeneous Integration. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 2061-2068.	2.5	4
2	Microfabrication, Coil Characterization, and Hermetic Packaging of Millimeter-Sized Free-Floating Neural Probes. IEEE Sensors Journal, 2021, 21, 13837-13848.	4.7	5
3	A Die-Level, Replaceable Integrated Chiplet (PINCH) Assembly Using a Socketed Platform, Compressible MicroInterconnects, and Self-Alignment. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 2069-2076.	2.5	2
4	Polyolithic Integration of 2.5-D and 3-D Chiplets Enabled by Multi-Height and Fine-Pitch CMIs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1474-1481.	2.5	4
5	Fiber-Interconnect Silicon Chiplet Technology for Self-Aligned Fiber-to-Chip Assembly. IEEE Photonics Technology Letters, 2019, 31, 1311-1314.	2.5	8
6	Heterogeneous Multi-Die Stitching Enabled by Fine-Pitch and Multi-Height Compressible Microinterconnects (CMIs). IEEE Transactions on Electron Devices, 2018, 65, 2957-2963.	3.0	11
7	Thermomechanical Analysis and Package-Level Optimization of Mechanically Flexible Interconnects for Interposer-on-Motherboard Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 2081-2089.	2.5	7
8	Flexible Interconnect Design Using a Mechanically-Focused, Multi-Objective Genetic Algorithm. Journal of Microelectromechanical Systems, 2018, 27, 677-685.	2.5	6
9	A Disposable and Self-Aligned 3-D Integrated Bio-Sensing Interface Module for CMOS Cell-Based Biosensor Applications. IEEE Electron Device Letters, 2018, 39, 1215-1218.	3.9	3
10	Design, Fabrication, and Characterization of Dense Compressible Microinterconnects. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1003-1010.	2.5	14
11	Dense and Highly Elastic Compressible MicroInterconnects (CMIs) for Electronic Microsystems. , 2017, , .		3
12	A microfabricated electronic microplate platform for low-cost repeatable biosensing applications. , 2015, , .		3